Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1872	insulation adj layer with silicon adj nitride	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:18
L2	175	L1 and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:46
L3	183	passivation adj layer.ti.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:50
L4	170	passivation adj layer with silicon adj nitride with conventional	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:08
L5	3	L4 and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:50
L6	18	("4347265" | "4580877" | "4772885" | "4877995" | "4929060" | "5101289" | "5280221" | "5300928").PN. OR ("5504599").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:54
L7	7	("4500173" | "4772885" | "5121234" | "5504599" | "5841494" | "5852485").PN. OR ("6208391").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:55
L8	186	passivation adj layer with silicon adj nitride with convention$	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:09
L9	3	L8 and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:08
L10	3803	silicon adj nitride with dielectric adj constant	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:09
L11	177	L10 and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:10
L12	0	insulation adj layer with silicon adj nitride with convention	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:18
L13	29	insulation adj layer with silicon adj nitride with convention$	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:21
L14	192	electroluminescent and electrode and passivation adj layer and nitride	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:21

L15	33	L14 and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:56
L16	23	organic adj electroluminescent and 349/69.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 15:59
L17	95	organic.ti. and "349"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 16:58
L18	1	"6830494".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 16:58
S1	1	"10/653914"	US-PGPUB; USPAT	OR	ON	2005/02/02 11:11
S2	1086	349/43.ccls.	US-PGPUB; USPAT	OR	ON	2005/01/18 18:29
S4	60	"349"/$.ccls. and without adj5 "contact hole"	US-PGPUB; USPAT	OR	ON	2005/01/18 19:31
S5	362	"349"/$.ccls. and "gate pad" and "data pad"	US-PGPUB; USPAT	OR	ON	2005/01/19 15:43
S6	4322	"contact hole".ab.	US-PGPUB; USPAT	OR	ON	2005/01/19 15:44
S7	334	S6 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/01/19 15:44
S8	59	expose with without with contact with hole	US-PGPUB; USPAT	OR	ON	2005/01/19 15:45
S9	9	expose with without adj5 contact adj hole	US-PGPUB; USPAT	OR	ON	2005/01/19 15:46
S10	37	expos$ with without adj5 contact adj hole	US-PGPUB; USPAT	OR	ON	2005/01/19 16:28
S11	2	expos$ with without adj5 contact adj hole and "gate pad" and "data pad"	US-PGPUB; USPAT	OR	ON	2005/01/19 16:29
S12	7	US-5929958-$.DID. OR US-5034339-$.DID. OR US-5034340-$.DID. OR US-5045485-$.DID. OR US-5065202-$.DID. OR US-4960719-$.DID. OR US-5703668-$.DID.	US-PGPUB; USPAT	OR	ON	2005/01/28 15:58
S13	3	("5065202").URPN.	USPAT	OR	ON	2005/01/28 15:58
S14	9	("20010008710" | "5065202" | "5691787" | "5731856" | "5852488" | "5972527" | "6259490" | "6295109" | "6444296").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 16:04

S15	1	"09/526150"	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 16:06
S16	6	"gate pad" and "data pad" and (without adj5 (contact adj hole))	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 17:11
S22	0	"forming a common electrode on the second"	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 16:22
S23	0	"10/626767"	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 17:12
S24	2	"626767".ap.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 17:12
S25	31	sung-chae-gee.in.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 18:41
S26	118	expose adj5 ("gate pad" and "data pad")	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 19:04
S27	4	lee-kun-jong	US-PGPUB; USPAT	OR	ON	2005/01/28 19:36
S28	4	lee-kun-jong.in.	US-PGPUB; USPAT	OR	ON	2005/01/28 19:37
S29	1	"20050012150"	US-PGPUB; USPAT	OR	ON	2005/01/31 15:50
S30	0	etch and (polish$ adj process) and (dry adj etch) and (atmospher$ adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/01/31 15:51
S31	0	(polish$ adj process) and (dry adj etch) and (atmospher$ adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/01/31 15:52
S32	73	(polishing adj process) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/01/31 15:53
S33	223	(common adj electrode) with opposed with (pixel adj electrode)	US-PGPUB; USPAT	OR	ON	2005/01/31 15:54
S34	159	(common adj electrode) with opposed with (pixel adj electrode) and "active matrix"	US-PGPUB; USPAT	OR	ON	2005/01/31 16:01
S35	3	(common adj electrode) with opposed with (pixel adj electrode) same conventional and "active matrix"	US-PGPUB; USPAT	OR	ON	2005/01/31 16:03
S36	37	(common adj electrode) with oppos$ with (pixel adj electrode) same conventional and "active matrix"	US-PGPUB; USPAT	OR	ON	2005/01/31 18:35

S37	5	positive adj mask and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/01/31 18:36
S38	146	positive adj (resist mask) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/01/31 18:37
S39	12	(US-20010048489-$ or US-20020033905-$ or US-20020044229-$ or US-20020051110-$ or US-20020101556-$ or US-20020121639-$ or US-20030123009-$ or US-20030193626-$ or US-20030197182-$ or US-20050012150-$).did. or (US-6611310-$ or US-6649936-$).did.	US-PGPUB; USPAT	OR	ON	2005/02/01 11:39
S40	57	(data adj pad) and (data adj pad adj terminal)	US-PGPUB; USPAT	OR	ON	2005/02/01 14:43
S41	57	(data adj pad adj terminal)	US-PGPUB; USPAT	OR	ON	2005/02/01 16:48
S42	0	seiko.as. and "gate pad" and "data pad"	US-PGPUB; USPAT	OR	ON	2005/02/01 15:34
S43	85	philips.as. and "gate pad" and "data pad"	US-PGPUB; USPAT	OR	ON	2005/02/01 15:42
S44	22	S43 and terminal	US-PGPUB; USPAT	OR	ON	2005/02/01 15:43
S45	27	chang-youn-gyoung.in.	US-PGPUB; USPAT	OR	ON	2005/02/01 16:32
S46	3	(data adj pad adj terminal) with (protect shield)	US-PGPUB; USPAT	OR	ON	2005/02/01 17:19
S47	3	((dip dipping) with etchant) and polish$ adj method	US-PGPUB; USPAT	OR	ON	2005/02/01 17:34
S48	797	(passivation adj layer) with (entire adj surface)	US-PGPUB; USPAT	OR	ON	2005/02/01 17:53
S49	221	(passivation adj layer) with (entire adj surface) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 18:05
S50	0	(passivation adj layer) with (entire adj surface) adj to and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 18:05
S51	0	(passivation adj layer) and polyminide	US-PGPUB; USPAT	OR	ON	2005/02/01 18:34
S52	4152	(passivation adj layer) and polyimide	US-PGPUB; USPAT	OR	ON	2005/02/01 18:35
S53	1220	(passivation adj layer) with polyimide	US-PGPUB; USPAT	OR	ON	2005/02/01 18:36
S54	315	S52 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 18:37

S55	98	S53 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 18:50
S56	23	"dipping process" and "349"/.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 18:58
S57	25	("dipping process" (dip with etchant)) and "349"/.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 19:00
S58	12	("dipping process" (dip with etchant)) and "349"/.ccls. and etch$	US-PGPUB; USPAT	OR	ON	2005/02/01 19:17
S59	207	dip with etchant	US-PGPUB; USPAT	OR	ON	2005/02/01 19:17
S60	3	S59 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 19:37
S61	10	dipping with etchant and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 19:45
S62	22	dipping with etchant and (polishing adj process)	US-PGPUB; USPAT	OR	ON	2005/02/01 19:54
S63	21753	etch$ same (CMP (chemical adj mechanical adj polish$))	US-PGPUB; USPAT	OR	ON	2005/02/02 10:18
S64	105	S63 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/01 19:55
S65	13631	etch$ with (CMP (chemical adj mechanical adj polish$))	US-PGPUB; USPAT	OR	ON	2005/02/02 10:11
S66	57	S65 and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 10:18
S67	1289	dry adj etch$ and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 10:25
S68	4	(dry adj etch$ with atmospheric adj pressure adj plasma) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 10:27
S69	5	(etch$ with atmospheric adj pressure adj plasma) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 10:28
S70	15	(atmospher$ adj pressure adj plasma) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 10:29
S71	468	(atmospher$ adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/02/02 10:39
S72	1	(atmospher$ adj pressure adj plasma) and (beam adj type)	US-PGPUB; USPAT	OR	ON	2005/02/02 10:40
S73	2	plasma and (beam adj type) and (bar adj type)	US-PGPUB; USPAT	OR	ON	2005/02/02 10:42
S74	526	etch and (low adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/02/02 11:11
S75	1	etch and (low adj pressure adj plasma) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 11:12

S76	83	etch with (low adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/02/02 13:04
S77	0	etch with (low adj pressure adj plasma) and "liquid crystal"	US-PGPUB; USPAT	OR	ON	2005/02/02 13:04
S78	175	etch same (low adj pressure adj plasma)	US-PGPUB; USPAT	OR	ON	2005/02/02 13:05
S79	38	etch same (low adj pressure adj plasma) same convention$	US-PGPUB; USPAT	OR	ON	2005/02/02 13:13
S80	0	(passivation adj layer) with polyminide and rubbing and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:14
S81	51	(passivation adj layer) with polyimide and rubbing and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:14
S82	3	(passivation adj layer) with polyimide and rubbing and "349"/$.ccls. and (passivation adj layer) with (entire adj surface)	US-PGPUB; USPAT	OR	ON	2005/02/02 13:15
S83	51	(passivation adj layer) with polyimide and rubbing and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:16
S84	54	(passivation adj layer) with (entire adj surface) and rubbing and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:23
S85	3	S83 and S84	US-PGPUB; USPAT	OR	ON	2005/02/02 13:16
S86	221	(passivation adj layer) with (entire adj surface) and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:47
S87	15742	slit and mask	US-PGPUB; USPAT	OR	ON	2005/02/02 13:48
S88	321	slit with mask and "349"	US-PGPUB; USPAT	OR	ON	2005/02/02 13:48
S89	321	slit with mask and "349"	US-PGPUB; USPAT	OR	ON	2005/02/02 13:49
S90	8	half adj transmit$ with mask and slit and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:50
S91	8	half adj transmit$ with slit and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:50
S92	11	half adj transmi$ with slit and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/02 13:51
S93	1	"20050012150"	US-PGPUB; USPAT	OR	ON	2005/07/11 18:20
S94	2203	257/347.ccls.	US-PGPUB; USPAT	OR	ON	2005/07/11 18:22
S95	0	"6943048".pn.	US-PGPUB; USPAT	OR	ON	2005/07/11 18:23

S96	1	"6493048".pn.	US-PGPUB; USPAT	OR	ON	2005/07/11 18:25
S97	1	"4345249".pn.	US-PGPUB; USPAT	OR	ON	2005/07/11 18:27
S98	1	10/653914	US-PGPUB; USPAT	OR	ON	2005/07/11 18:37
S99	1	10/481236	US-PGPUB; USPAT	OR	ON	2005/07/11 18:38
S100	2	byun-jae-seong.in.	US-PGPUB; USPAT	OR	ON	2005/07/12 13:40
S101	1	"6342938".pn.	US-PGPUB; USPAT	OR.	ON	2005/07/12 14:01
S102	1	"6035526".pn.	US-PGPUB; USPAT	OR	ON	2005/07/12 15:46
S103	29	ink with pixel adj electrode and "349"/$.ccls.	US-PGPUB; USPAT	OR	ON	2005/07/12 16:17
S104	1224	349/113.ccls.	US-PGPUB; USPAT	OR	ON	2005/07/12 16:30
S105	2610	349/42-43.ccls. 349/149,152.ccls.	US-PGPUB; USPAT	OR	ON	2005/07/12 16:30
S106	3	("6038003" | "6091466" | "6414730").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 16:39
S107	3	("20030112387" | "20030180978" | "5825449").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 16:53
S108	1	10/653914	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 16:53
S109	4	("5760854" | "5781254" | "5940151" | "6091466").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 17:50
S110	5	("5272355" | "5482173" | "5907379" | "6287899" | "6391499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 18:49
S111	4	09/779705	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 15:40
S112	1	"5909266".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 15:42
S113	1	"5767827".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 15:44
S114	1	"4676868".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 15:52

S116	1	passivation adj layer with printing adj method with convention$	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 16:10
S117	1	10/779705	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 16:10
S118	4	09/779705	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:19
S119	1	"4500173".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:30
S120	1	"6819368".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:34
S121	1	10/613712	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:35
S122	1	2003/0067266	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:36
S123	1	"20030067266"	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:38
S124	64	kato-yoshifumi.in.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:42
S125	158	349/69.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:42
S126	6	("6114805" | "6121726" | "6433487" | "6507379" | "6521912" | "6731064").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:54
S127	1	10/658846	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 17:54
S128	0	("6542207").URPN.	USPAT	OR	ON	2005/07/13 18:02
S129	7	("4500173" | "4772885" | "5121234" | "5504599" | "5841494" | "5852485").PN. OR ("6208391").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 18:15
S130	18	("4347265" | "4580877" | "4772885" | "4877995" | "4929060" | "5101289" | "5280221" | "5300928").PN. OR ("5504599").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 14:17